



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



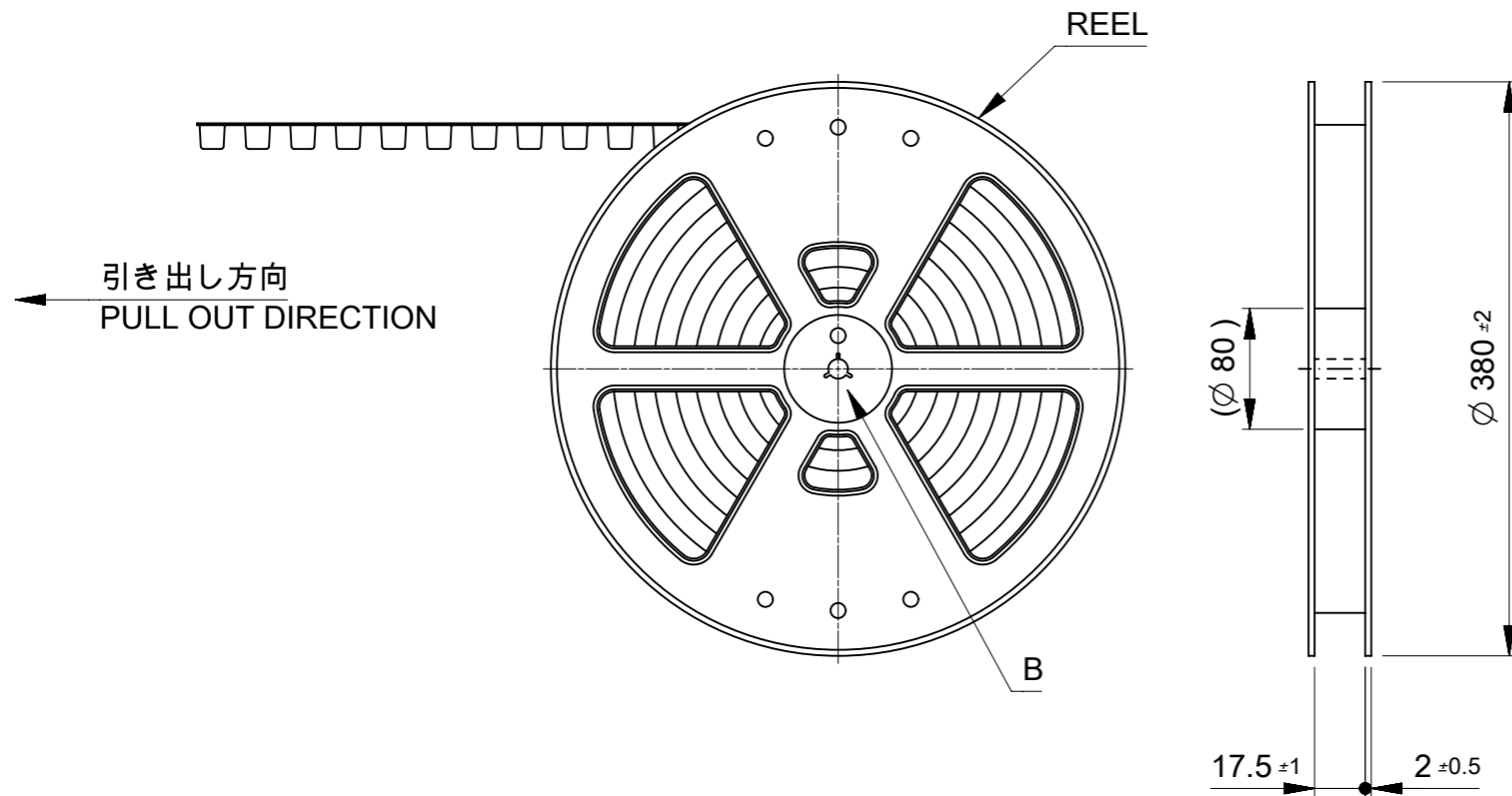
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

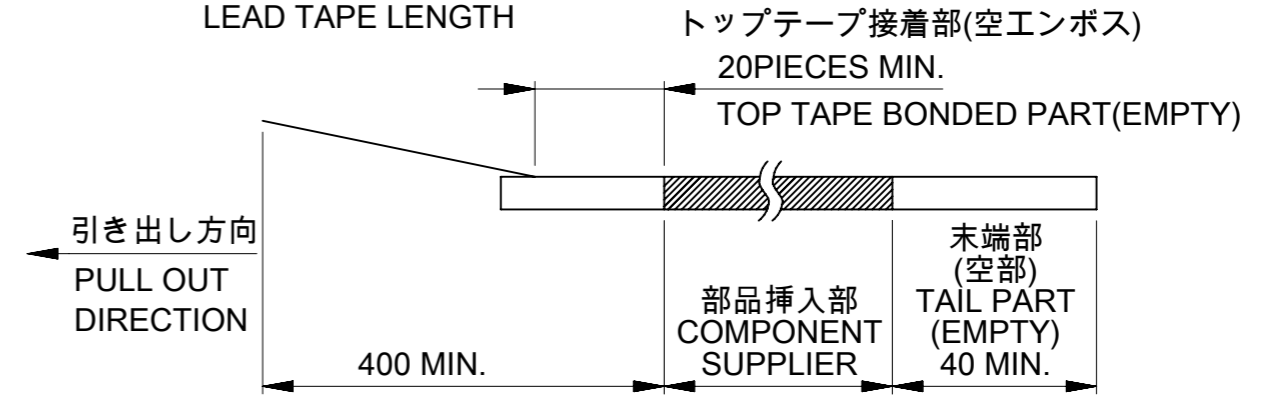
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





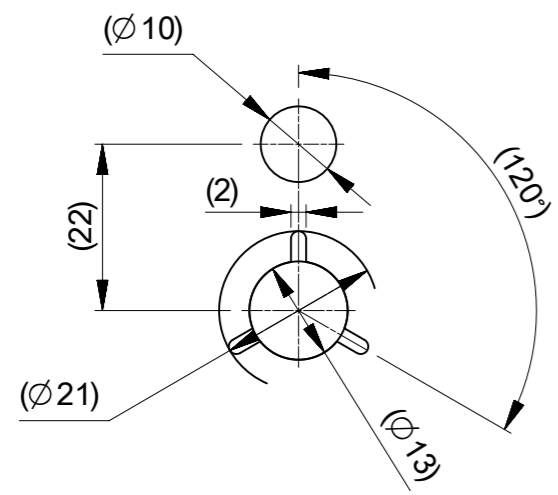
NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量 : 1300個 / リール
NUMBER OF CONNECTORS : 1300PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH



4.材料

MATERIAL
 キャリアテープ : ポリスチレン (PS)
 CARRIER TAPE : POLYSTYRENE
 トップテープ : ポリエステル (PET)、その他
 TOP TAPE : POLYESTER (PET), OTHER
 リール : ポリスチレン (PS) <リサイクル材を含む>
 REEL : POLYSTYRENE <RECYCLE MATERIAL CONTAINED>

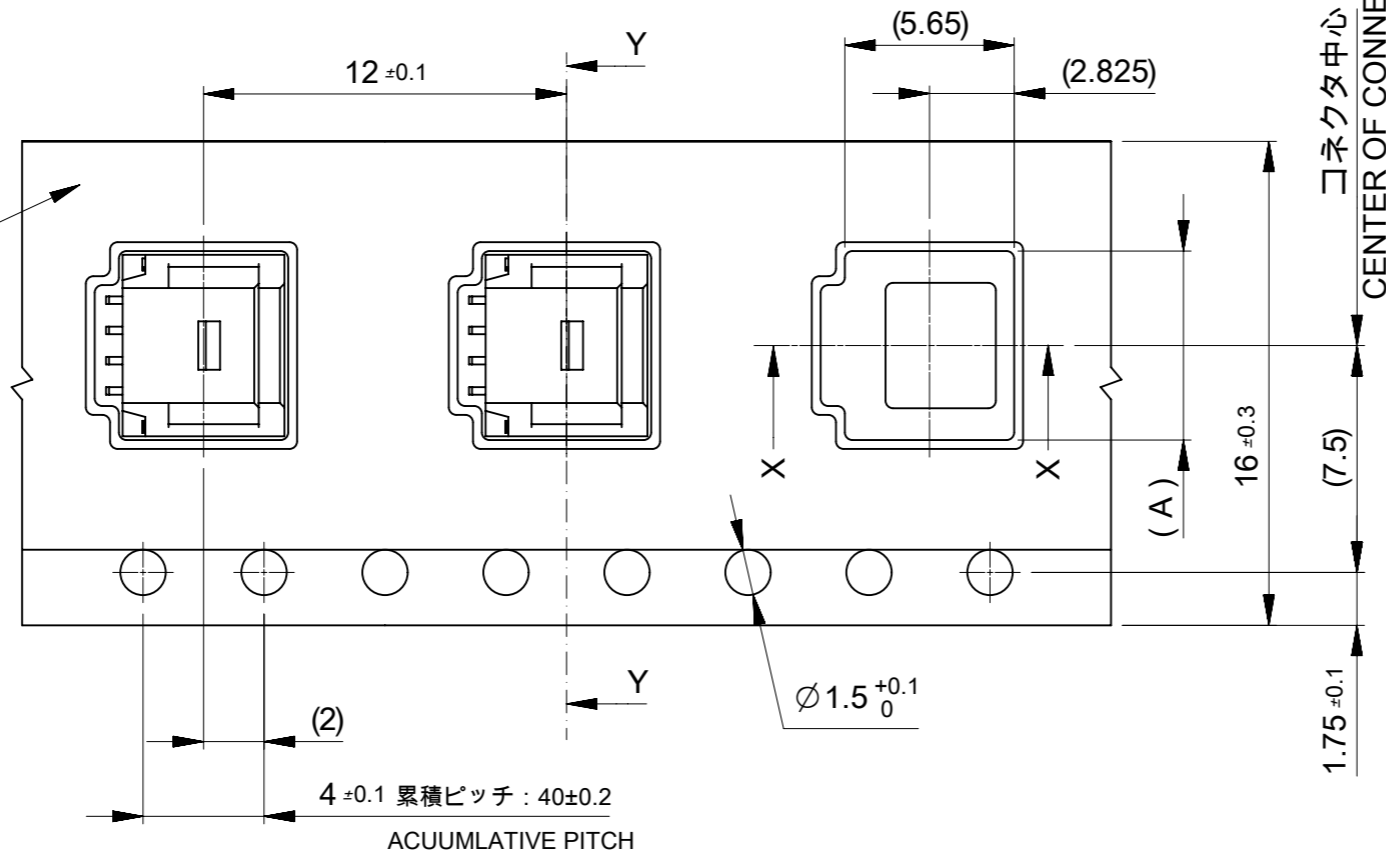


DETAIL B

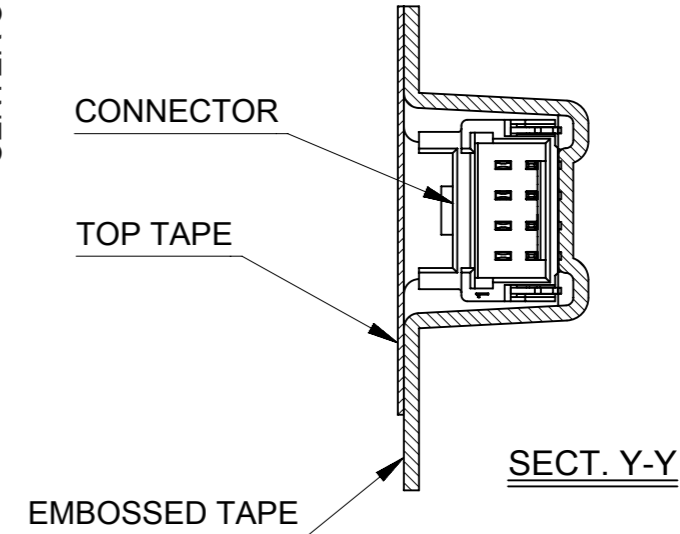
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

EC NO: 168346 DRWN: KYAMADA02 CHK'D: SAKIYAMA APPR: TKANEKO	2017/11/27 2017/11/30 2017/12/01	GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL $\pm 3.0^\circ$	DIMENSION UNITS: mm SCALE: NTS			
	4 PLACES ± 0.2 3 PLACES ± 0.2 2 PLACES ± 0.2 1 PLACE ± 0.2 0 PLACES ± 0.2	DRWN BY: KYAMADA02 DATE: 2017/11/27	CHK'D BY: SAKIYAMA DATE: 2017/11/30			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPR BY: TKANEKO DATE: 2017/12/01	DRAWING SIZE: A3 THIRD ANGLE PROJECTION	PRODUCT CUSTOMER DRAWING		
	A	REV	DRAWING SIZE: A3 THIRD ANGLE PROJECTION	SERIES: 501953 MATERIAL NUMBER: SEE CHART CUSTOMER: GENERAL	DOCUMENT NUMBER: 5019530305-SD DOC TYPE: PSD DOC PART: 000 SHEET NUMBER: 1 OF 2	

16幅テープ
16 WIDTH TAPE

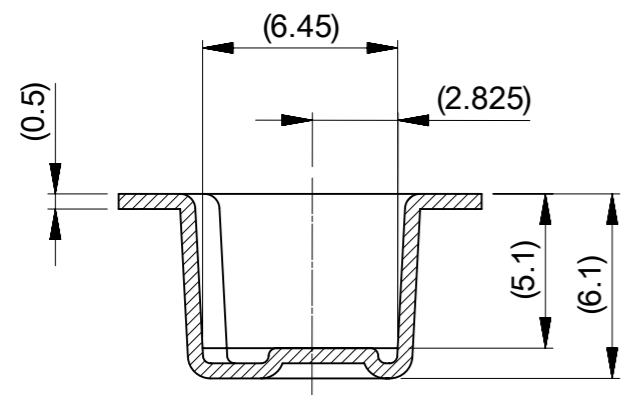


コネクタ中心
CENTER OF CONNECTOR



EMBOSSSED TAPE

SECT. Y-Y

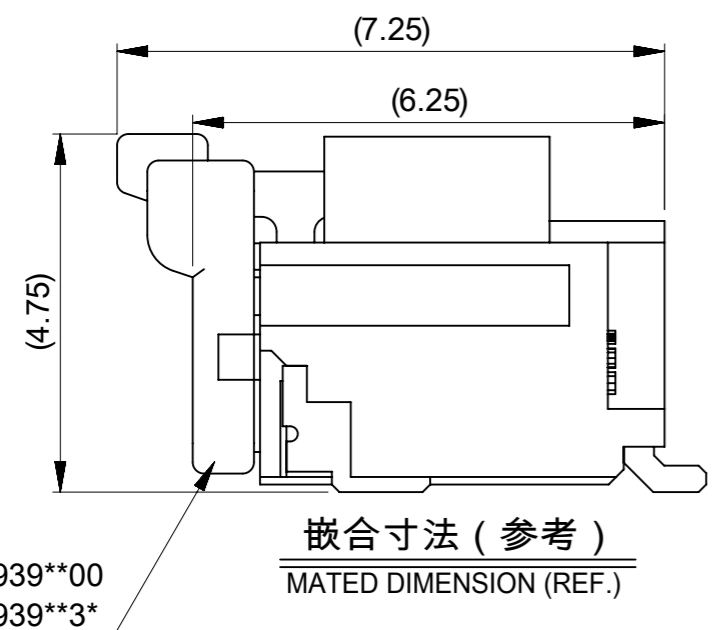
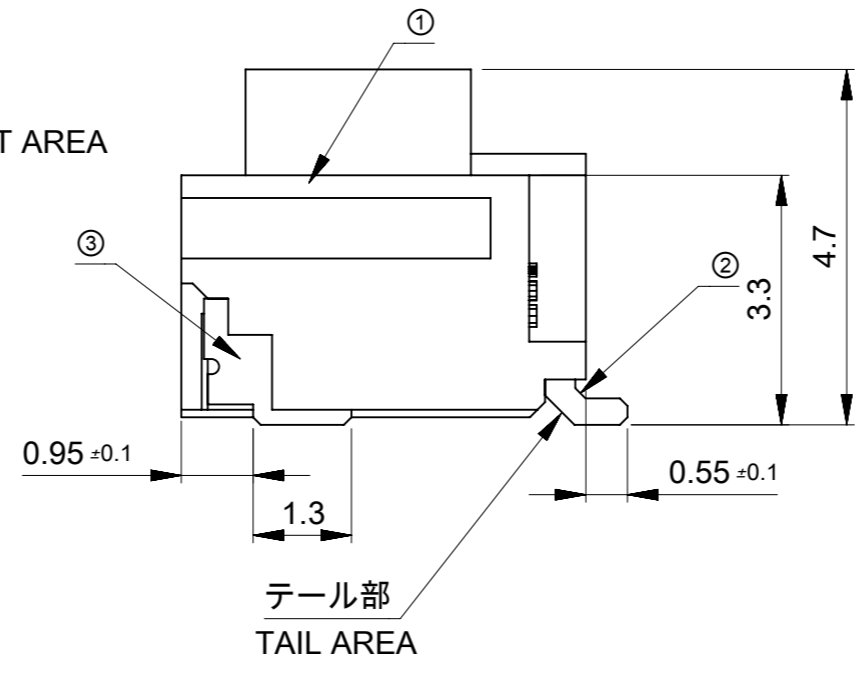
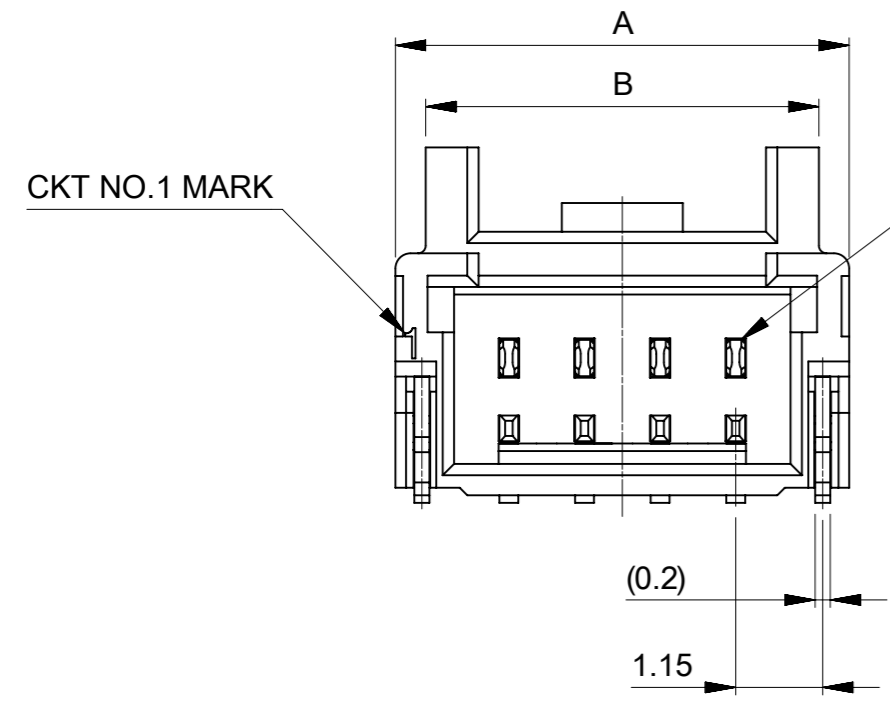
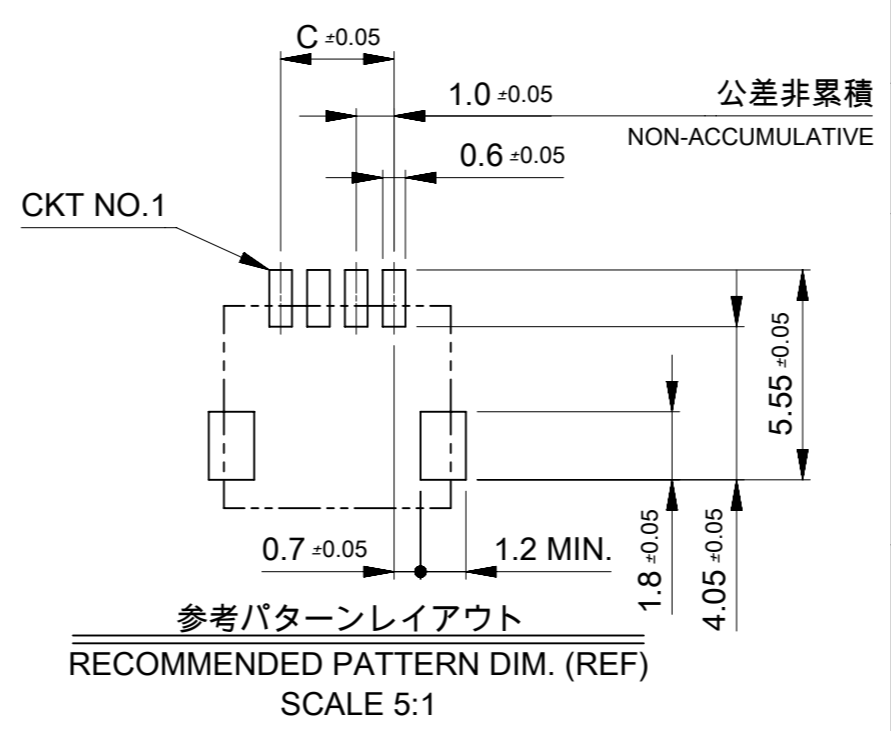
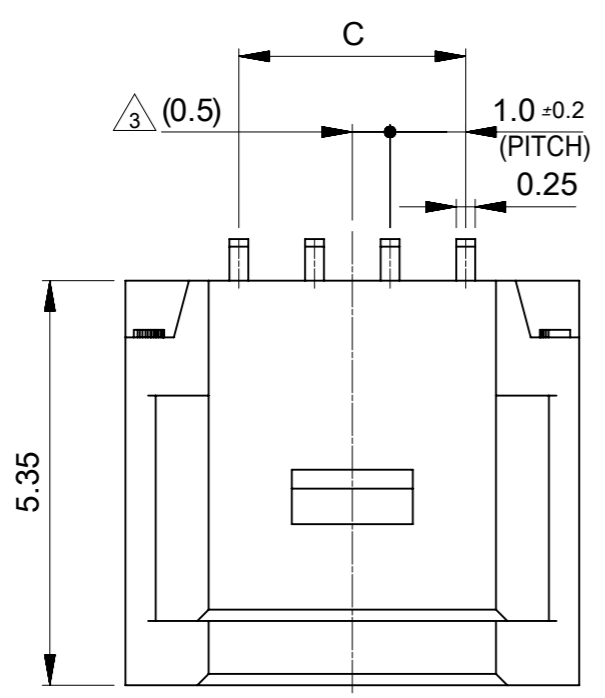


SECT. X-X

7.3	5019530505	5
6.3	5019530405	4
5.3	5019530305	3
(A)	EMBOSSSED PACKAGE	極数
	オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES NO. 501953**06		

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

EC NO: 168346 DRWN: KYAMADA02 CHK'D: SAKIYAMA APPR: TKANEKO	2017/11/27 2017/11/30 2017/12/01	GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± 3.0 ° 4 PLACES ± 0.2 3 PLACES ± 0.2 2 PLACES ± 0.2 1 PLACE ± 0.2 0 PLACES ± 0.2	DIMENSION UNITS: mm SCALE: NTS DRWN BY: KYAMADA02 DATE: 2017/11/27 CHK'D BY: SAKIYAMA DATE: 2017/11/30 APPR BY: TKANEKO DATE: 2017/12/01	molex PICO-CLASP 1.0W/B SINGLE-ROW R/A OUTER LOCK EMBSTP PKG(GOLD VERSION 0.1)
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWING SIZE: A3 THIRD ANGLE PROJECTION	PRODUCT CUSTOMER DRAWING
			SERIES: 501953 MATERIAL NUMBER: SEE CHART CUSTOMER: GENERAL	
			DOCUMENT NUMBER: 5019530305-SD DOC TYPE: PSD DOC PART: 000 SHEET NUMBER: 2 OF 2	



番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	ポリアミド UL94V-0 色 : 自然色 POLYAMIDE, UL94V-0, COLOR:NATURAL
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 金めっき(接触部) : 0.1 MICRO METER MIN. GOLD PLATING (CONTACT AREA) 金めっき(テール部):0.05 MICRO METER MINIMUM. GOLD PLATING (TAIL AREA) ニッケルめっき(下地):1.0 MICRO METER MIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	黄銅 BRASS 錫めっき:1.0 MICRO METER MIN. TIN ニッケルめっき(下地):1.0 MICRO METER MIN. NICKEL(UNDER PLATING)

NOTES.
 1.嵌合相手 : 501939****
 MATE WITH :501939****
 2.ソルダーピン及びネイル平坦度は、0.1MAX.
 SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
 ③ 極数 = 偶数に適用
 APPLY FOR CKT SIZE=EVEN

4.0	5.2	7.0	5019530505	5
3.0		6.0	5019530405	4
2.0	4.2	5.0	5019530305	3
C	B	A	EMBOSSED PACKAGE	極数
			オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES NO. 501953**06				

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

EC NO: 168346 DRWN: KYAMADA02 CHK'D: SAKIYAMA APPR: TKANEKO	2017/11/27	2017/11/30	2017/12/01	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE			
				ANGULAR TOL ± 3.0 °	mm	10:1			
	4 PLACES	± 0.2			DRWN BY	DATE		PICO-CLASP 1.0W/B SINGLE-ROW RA OUTER LOCK WAFER ASSY(GOLD VERSION 0.1)	
	3 PLACES	± 0.2		KYAMADA02	2017/11/27				
	2 PLACES	± 0.2		CHK'D BY	DATE				
1 PLACE	± 0.2		SAKIYAMA	2017/11/30					
0 PLACES	± 0.2		APPR BY	DATE		PRODUCT CUSTOMER DRAWING			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				TKANEKO	2017/12/01				
DRAWING SIZE		THIRD ANGLE PROJECTION							
A3						SERIES	MATERIAL NUMBER	CUSTOMER	
						501953	SEE TABLE	GENERAL	
						DOCUMENT NUMBER	DOC TYPE	DOC PART	SHEET NUMBER
						5019530306-SD	PSD	000	1 OF 1

10

9

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7

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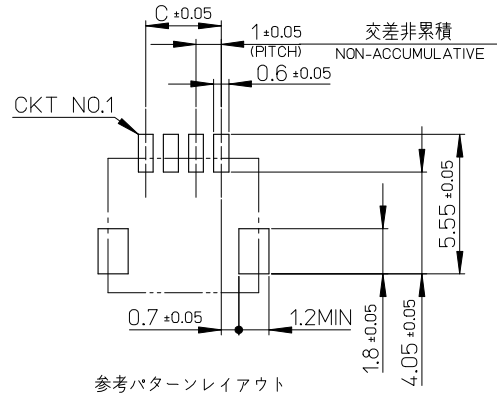
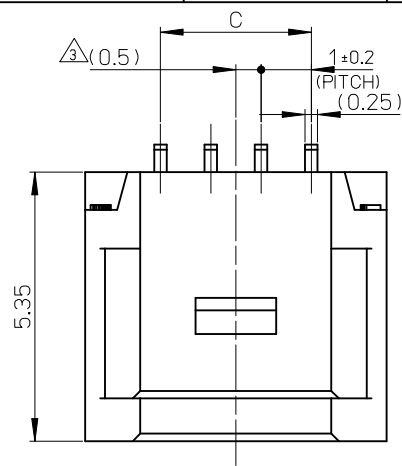
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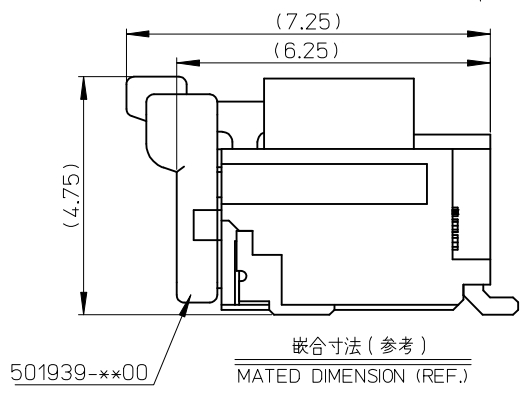
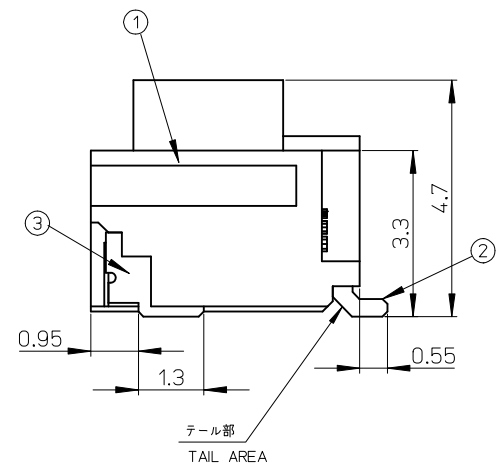
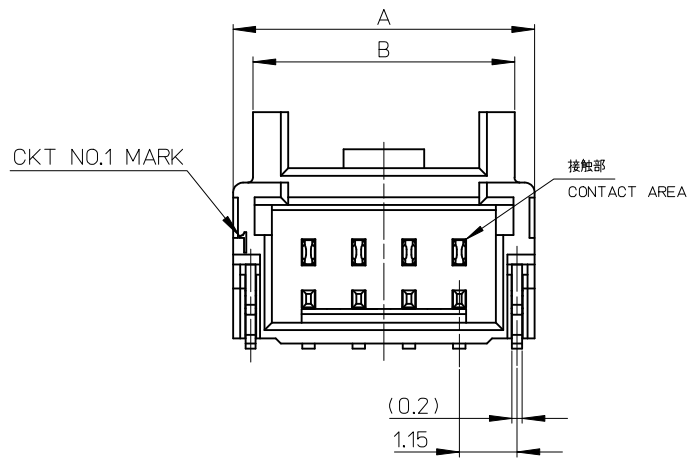
3

2

1



参考パターンレイアウト
RECOMMENDED PATTERN DIM. (REF)
SCALE 5:1



番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン樹脂 UL94V-0 色:表参照 HEAT RESISTANCE NYLON .COLOR:SEE TABLE UL94V-0
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 金メッキ(接触部):0.1μm MIN. GOLD PLATING (CONTACT AREA) 金メッキ(テール部):0.05μm MIN. GOLD PLATING (TAIL AREA) ニッケルメッキ(下地):1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	黄銅 BRASS 錫メッキ:1.0μmMIN. TIN ニッケルメッキ(下地):1.0μmMIN. NICKEL(UNDER PLATING)

NOTES.

1. 嵌合相手: 501939-****
MATE WITH: 501939-****
2. ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
3. 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
4. ELV AND RoHS COMPLIANT.

4.0	5.2	7.0	5
3.0		6.0	4
2.0	4.2	5.0	3
C	B	A	極数 CIRCUITS

CONFIDENTIAL

CONNECTOR SERIES No. 501953-***6
SCALE 10:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION

TITLE 1.0 WIRE TO BOARD CONN.
WAFER ASS'Y 1-ROW R/A
POSI-LOCK

molex

DOCUMENT NO. SD-501953-003 SHEET NO. 1 OF 2

REVISED	EC NO.	DRWNR	CHKD	APPR	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE	
						UNDER	OVER	ANGULAR	MM ONLY	
A	J2016-1063	DRWNR: TANAKA02	CHKD: SAKIYAMA	APPR: IKANEKO	2016/04/07 2016/04/08 2016/04/28	0.25 UNDER	0.5 UNDER	±0.03	DRAWN BY	DATE
						0.25 OVER	1.0 UNDER	±0.05	KCHIKANO	2014/12/25
						0.5 OVER	10 UNDER	±0.1	CHECKED BY	DATE
						1.0 OVER	30 UNDER	±0.2	KASAKAWA	2014/12/25
						10 OVER		±0.25	APPROVED BY	DATE
						30 OVER		±0.3	NUKITA	2015/01/16
									MATERIAL NO.	
									SEE SHEET 2	
									SIZE	A3
									THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

9

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3

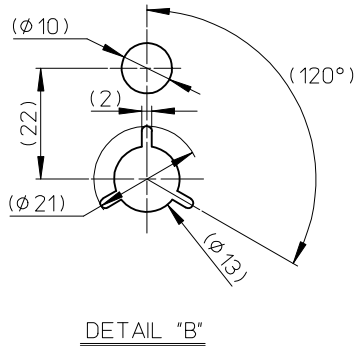
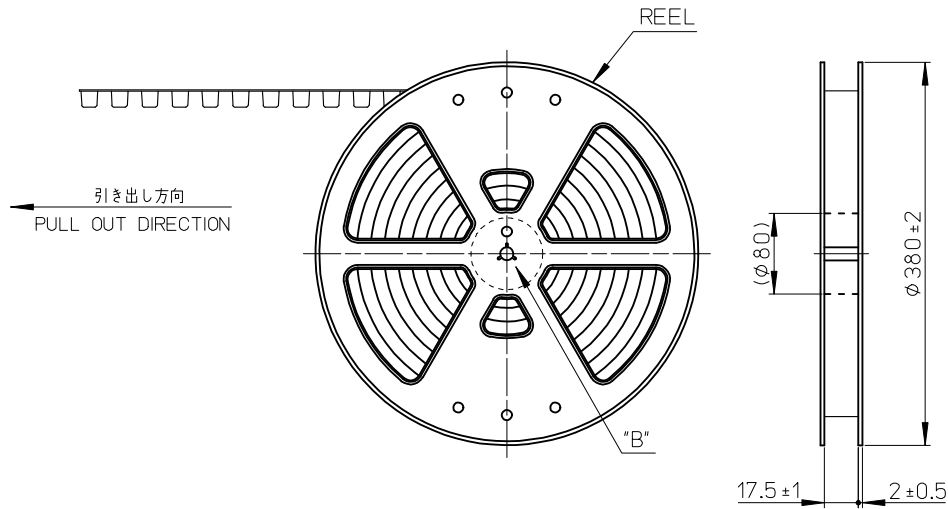
2

1

CONFIDENTIAL

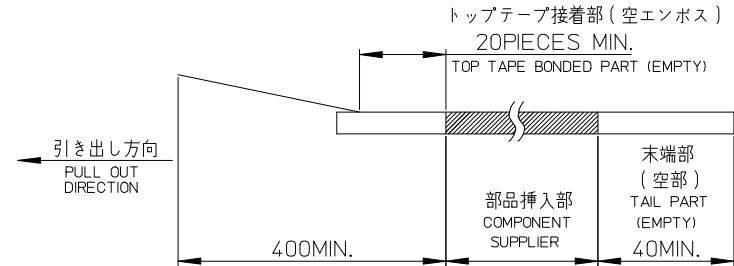
紫 PA46 VIOLET	橙 PA46 ORANGE	茶 PA46 BROWN	緑 PA46 GREEN	色 COLOR
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	5
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	4
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	3
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	極数 CIRCUITS
CONNECTOR SERIES No. 501953-***9				
青 PA46 BLUE	黄 PA46 YELLOW	赤 PA46 RED	黒 PA46 BLACK	自然色 PA6T NATURAL
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.
EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE	EMBOSSED PACKAGE
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.
CONNECTOR SERIES No. 501953-***6				

REVISED EC NO: J2016-1063 DRWR: TANKA02 2016/04/07 CHKD: SAKIYAMA 2016/04/08 APPR: KANEKO 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	KCHIKANO	2014/12/25	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A POSI-LOCK		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE			
	1.0 OVER	10 UNDER	±0.2	KASAKAWA	2014/12/25			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE				
30 OVER		±0.3	NUKITA	2015/01/16	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
ANGULAR	±3 °		SEE CHART		SD-501953-003		2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



NOTES

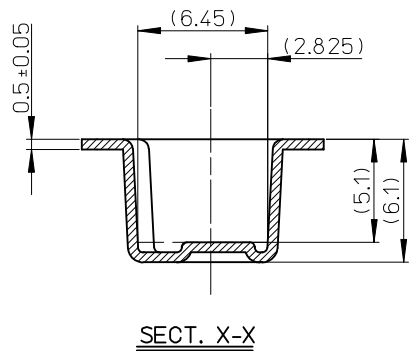
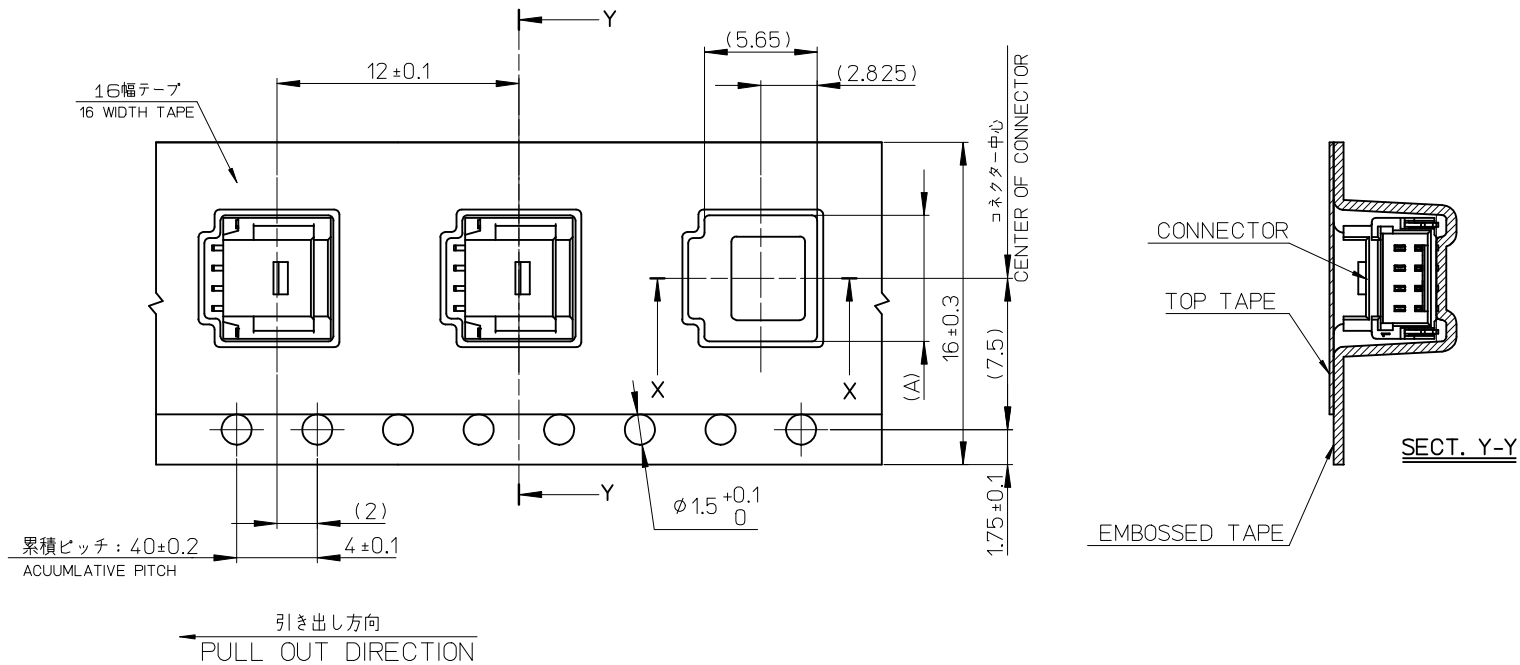
- 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量: 1300個/リール
NUMBER OF CONNECTORS: 1300PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
MATERIAL
キャリアテープ: ポリスチレン
CARRIER TAPE: POLYSTYRENE
トップテープ: PET、その他
TOP TAPE: PET, OTHER
リール: ポリスチレン<リサイクル材を含む>
REEL: POLYSTYRENE <RECYCLE MATERIAL CONTAINED >
- ELV AND RoHS COMPLIANT.
- ハイバリア梱包 (シリカゲル入り) 対応品である。(501953-**07除く)
THIS PRODUCT IS HIGH BARRIER PACKAGE.(WITH SILICAGEL)
(BESIDES 501953-**07)
- 開梱後の保管条件に注意のこと。(ハイバリア品対象: PS-501940-001参照)
REFER TO PS-501940-001(HIGH BARRIER PRODUCT)
FOR CONDITIONS AFTER OPEN.

REVISED EC NO: J2016-1063 DRWR: TANKA02 2016/04/07 CHKD: SAKIYAMA 2016/04/08 APPR: KANEKO 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	± 0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	± 0.05	KCHIKANO	2014/12/25	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG molex		
	0.5 OVER	1.0 UNDER	± 0.1	CHECKED BY	DATE			
	1.0 OVER	10 UNDER	± 0.2	KASAKAWA	2014/12/25	MATERIAL NO. SEE SHEET 3 DOCUMENT NO. SD-501953-004 SHEET NO. 1 OF 3		
	10 OVER	30 UNDER	± 0.25	APPROVED BY	DATE			
30 OVER		± 0.3	NUKITA	2015/01/16				
ANGULAR	± 3 °		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
A	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

CONFIDENTIAL




7.3	5
6.3	4
5.3	3
(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501953-***6

REVISED EC NO: J2016-1063 DRWR: TANKA02 2016/04/07 CHKD: SAKIYAMA 2016/04/08 APPR: KANEKO 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	0.25 UNDER	UNDER	± 0.03	DRAWN BY KCHIKANO	DATE 2014/12/25	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG		
	0.25 OVER	0.5 UNDER	± 0.05	CHECKED BY KASAKAWA	DATE 2014/12/25			
	0.5 OVER	1.0 UNDER	± 0.1	APPROVED BY NUKITA	DATE 2015/01/16			
	1.0 OVER	30 UNDER	± 0.2	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
30 OVER		± 0.3	SEE SHEET 3	SD-501953-004	2 OF 3			
ANGULAR ± 3 °			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								

CONFIDENTIAL

	紫 VIOLET	橙 ORANGE	茶 BROWN	緑 GREEN	色 COLOR
					5
					4
					3
	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES No. 501953-***9					
	青 BLUE	黄 YELLOW	赤 RED	黒 BLACK	自然色 NATURAL
					501953-0505
					501953-0405
					501953-0305
	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUITS

REVISED EC NO: J2016-1063 DRWR: TANKA02 CHKD: SAKIYAMA APPR: KANEKO	2016/04/07 2016/04/08 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
		0.25 OVER	0.5 UNDER	±0.05	KCHIKANO	2014/12/25	1.0 WIRE TO BOARD CONN. WAFER ASS'Y 1-ROW R/A EMBSTP PKG		
		0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE			
		1.0 OVER	10 UNDER	±0.2	KASAKAWA	2014/12/25			
		10 OVER	30 UNDER	±0.25	APPROVED BY	DATE			
30 OVER		±0.3	NUKITA	2015/01/16	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
ANGULAR ±3 °			SEE CHART		SD-501953-004		3 OF 3		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				